

IN THE CLAIMS

This listing of claims will replace all prior versions and listing of claims in the application:

1. (Currently amended) An anisotropically conductive sheet formed as a connector suitable for use in electrically inspecting circuits, comprising:
an anisotropically conductive sheet body formed by an elastic polymeric substance of silicone rubber and having a plurality of conductive parts extending in a thickness-wise direction of the sheet body and an insulating part mutually insulating these conductive parts, and
a DLC film integrally formed so as to cover all of ~~on~~ one or both surfaces of the anisotropically conductive sheet body so as to cover at least the insulating part, wherein
surface resistivity of the DLC film is 1 x 10⁸ to 1 x 10¹⁴ Ω/□, and
thickness of the DLC film is 1 to 500 nm.

Claims 2-6 (Canceled).

7. (Currently amended) ~~The~~ An anisotropically conductive sheet according to claim 6 formed as a connector suitable for electrically inspecting integrated circuits formed on a wafer, wherein the comprising:
an anisotropically conductive sheet body formed by an elastic polymeric substance of silicone rubber and having a plurality of conductive parts extending in a thickness-wise direction of the sheet body and an insulating part mutually insulating these conductive parts,
a metal layer integrally formed on one surface of the anisotropically conductive sheet body so as to cover the conductive parts, and
a DLC film integrally formed so as to cover a ~~the~~ surface of the metal layer, wherein

surface resistivity of the DLC film is 1×10^8 to $1 \times 10^{14} \Omega/\square$, and

thickness of the DLC film is 1 to 500 nm.

8. (Currently amended) The anisotropically conductive sheet according to claim 6 or 7, wherein ~~the~~ surface resistivity of the metal layer is at most $1 \times 10^{-2} \Omega/\square$.

9. (Currently amended) The anisotropically conductive sheet according to claim [[6]] 7, wherein ~~the~~ thickness of the metal layer is 5 to 1,000 nm.

10. (Withdrawn) A process for producing an anisotropically conductive sheet, comprising: producing an anisotropically conductive sheet body formed by an elastic polymeric substance and having a plurality of conductive parts extending in a thickness-wise direction of the sheet body and an insulating part mutually insulating these conductive parts, and integrally forming a DLC film on one or both surfaces of the anisotropically conductive sheet body thus obtained by a PVD method so as to cover at least the insulating part.

11. (Withdrawn) The process according to claim 10 for producing the anisotropically conductive sheet, wherein the DLC film is formed at a temperature of at most 150.degree. C.

12. (Withdrawn) The process according to claim 10 or 11 for producing the anisotropically conductive sheet, wherein an ion etching treatment is conducted on a surface, on which the DLC film is to be formed, in the anisotropically conductive sheet body, and the DLC film is then formed.

13. (Original) An anisotropically conductive connector comprising a frame plate having openings and the anisotropically conductive sheet according to claim 1, which is arranged so as to close each of the openings in the frame plate and supported by an opening edge of the frame plate.

14. (Currently amended) An anisotropically conductive connector suitable for use in conducting electrical inspection of each of a plurality of integrated circuits formed on a wafer in a state of the wafer, which comprises: a frame plate, in which a plurality of openings have been formed correspondingly to regions, in which electrodes to be inspected have been arranged, in all the integrated circuits formed on the wafer, which is are each an object of inspection, and a plurality of anisotropically conductive sheets respectively arranged so as to close the openings in the frame plate and supported by their corresponding opening edges of the frame plate, wherein the anisotropically conductive sheets are each composed of the anisotropically conductive sheet according to claim 1.

15. (Currently amended) An anisotropically conductive connector suitable for use in conducting electrical inspection of each of a plurality of integrated circuits formed on a wafer in a state of the wafer, which comprises: a frame plate, in which a plurality of openings have been formed correspondingly to regions, in which electrodes to be inspected have been arranged, in a plurality of integrated circuits selected from among the integrated circuits formed on the wafer, which is are each an object of inspection, and a plurality of anisotropically conductive sheets respectively arranged so as to close the openings in the frame plate and supported by their

corresponding opening edges of the frame plate, wherein the anisotropically conductive sheets are each composed of the anisotropically conductive sheet according to claim 1.

16. ((Currently amended) A probe for circuit inspection, which comprises a circuit board for inspection, on ~~the~~ a surface of which inspection electrodes have been formed in accordance with a pattern corresponding to a pattern of electrodes to be inspected of circuits, which are objects of inspection, and the anisotropically conductive sheet according to claim 1, which is arranged on the surface of the circuit board for inspection.

17. (Currently amended) A probe for circuit inspection that is suitable for use in conducting electrical inspection of each of a plurality of integrated circuits formed on a wafer in a state of the wafer, which comprises:

a circuit board for inspection, on ~~the~~ a surface of which inspection electrodes have been formed in accordance with a pattern corresponding to a pattern of electrodes to be inspected in all the integrated circuits formed on the wafer, which is an object of inspection, and the anisotropically conductive connector according to claim 14, which is arranged on the surface of the circuit board for inspection.

18. (Currently amended) A probe for circuit inspection that is suitable for use in conducting electrical inspection of each of a plurality of integrated circuits formed on a wafer in a state of the wafer, which comprises:

a circuit board for inspection, on ~~the~~ a surface of which inspection electrodes have been formed in accordance with a pattern corresponding to a pattern of

electrodes to be inspected in a plurality of integrated circuits selected from among the integrated circuits formed on the wafer, which is an object of inspection, and the anisotropically conductive connector according to claim 15, which is arranged on the surface of the circuit board for inspection.

19. (Original) The probe for circuit inspection according to claim 17, wherein a sheet-like connector composed of an insulating sheet and a plurality of electrode structures each extending through in a thickness-wise direction of the insulating sheet and arranged in accordance with a pattern corresponding to the pattern of the inspection electrodes in the circuit board for inspection is arranged on the anisotropically conductive connector.

20. (Original) A circuit inspection apparatus comprising the probe for circuit inspection according to claim 16.